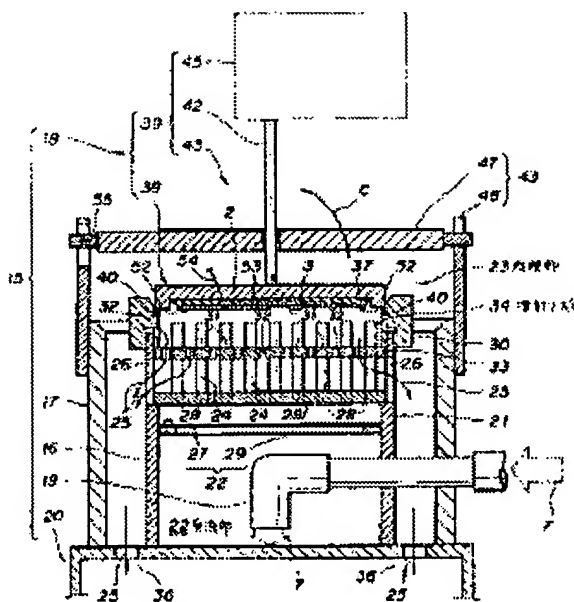


METHOD FOR PLATING SEMICONDUCTOR WAFER

Patent number: JP62297494
Publication date: 1987-12-24
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Classification:
 - international: C25D7/12; H01L21/288
 - european:
Application number: JP19860139314 19860617
Priority number(s):

Abstract of JP62297494

PURPOSE: To eliminate the directionality of a plating soln. current by supplying the plating soln. onto the semiconductor wafer as many plating soln. jets, and rotating and moving at least one between a plating soln. jet supply means and the surface of the semiconductor wafer to be plated with respect to the other.
CONSTITUTION: After the engagement of the gear of a driving force transmitting means 45 with the gear of a shaft 42 is released, a horizontal frame member 47, the shaft 42, and a fixing main body 38 are turned in the direction C through a rotary shaft 55 to open a treating part 23, the semiconductor wafer 2 is fixed by a fixing claw 52, and then the horizontal frame member 47, the fixing main body 38, etc., are turned in the reverse direction through the rotary shaft 55 to close the treating part 23. The wafer 2 is rotated by a rotating means 18, the plating soln. 7 is supplied to a soln. receiving part 22 from a pipe 19, and the plating soln. 7 is sent to an injection nozzle 34 through a feed hole 28, a feed pipe 24, and a feed hole 31. The plating soln. 7 is injected from many injection nozzles 34, and a plating soln. layer is formed over the whole surface 3 of the wafer 3.



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